

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5635343

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHAO ZHENG	11/18/2017
WEI WANG	11/10/2017

RECEIVING PARTY DATA	
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (SHANGHAI) CORPORATION
Street Address:	18 ZHANG JIANG ROAD, PUDONG NEW AREA
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201203
Name:	SEMICONDUCTOR MANUFACTURING INTERNATIONAL (BEIJING) CORPORATION
Street Address:	18 WEN CHANG AVENUE, ECONOMICAL-TECHNOLOGICAL DEVELOPMENT AREA
Internal Address:	DAXING DISTRICT
City:	BEIJING
State/Country:	CHINA
Postal Code:	100176

PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16521507

CORRESPONDENCE DATA	
Fax Number:	(415)576-0300
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4155760200
Email:	vaguilar@kilpatricktownsend.com
Correspondent Name:	KILPATRICK TOWNSEND AND STOCKTON LLP
Address Line 1:	TWO EMBARCADERO CENTER
Address Line 2:	SUITE 1900
Address Line 4:	SAN FRANCISCO, CALIFORNIA 94111

ATTORNEY DOCKET NUMBER:	087720-052410US-1149924
NAME OF SUBMITTER:	VANESSA M. AGUILAR
SIGNATURE:	/Vanessa M. Aguilar/
DATE SIGNED:	07/24/2019
Total Attachments: 3 source=Assigment_052410US#page1.tif source=Assigment_052410US#page2.tif source=Assigment_052410US#page3.tif	

ASSIGNMENT
(Patent Application)

We, the undersigned, have invented certain inventions and improvements disclosed in a utility (provisional or non-provisional) or design patent application entitled

**“LOW CONTACT RESISTANCE SEMICONDUCTOR STRUCTURE
AND METHOD FOR MANUFACTURING THE SAME”**

the specification of which is provided with this Assignment and identified by the Attorney Docket No. above.

For one dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which we acknowledge, we:

1. Agree to assign, transfer, convey, and sell, hereby assign, transfer, convey, and sell and have assigned, transferred, conveyed, and sold to **Semiconductor Manufacturing International (Shanghai) Corporation**, a corporation of the People’s Republic of China, having a principal place of business at 18 Zhang Jiang Road, Pudong New Area, Shanghai, 201203, People’s Republic of China *and* **Semiconductor Manufacturing International (Beijing) Corporation**, a corporation of the People’s Republic of China, having a principal place of business at 18 Wen Chang Road, Economical-Technological Development Area, Daxing District, Beijing, 100176, People’s Republic of China (“Assignees”), the entire right, title, and interest in and to:
 - (a) all intellectual property (including, without limitation, any innovation, information, invention, discovery, product, process, work or design) disclosed, embodied, shown, or claimed in the above-referenced patent application, implicitly or explicitly;
 - (b) the above-referenced patent application, the right to claim priority to the above-referenced patent application, all applications based in whole or in part upon the above-referenced patent application, including, without limitation, all applications that are a provisional, non-provisional, design, divisional, continuation, continuation-in-part, registration, utility model, industrial design, reissue, renewal, substitute, extension, reexamination, post-grant review, inter partes review, supplemental examination or non-U.S. patent application or application for other rights based in whole or in part on the above-referenced patent application;
 - (c) all patents (including, without limitation, all U.S. and non-U.S. patents, registrations, utility models, industrial designs, design patents,

ASSIGNMENT
**LOW CONTACT RESISTANCE SEMICONDUCTOR STRUCTURE AND
METHOD FOR MANUFACTURING THE SAME**

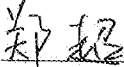
Attorney Docket No. 087720-052400US-1041630

Page 2 of 2

counterparts, continuations, continuations-in-part, divisionals, reissues, renewals, substitutes, extensions, reexaminations, post-grant reviews, inter partes reviews and supplemental examinations) that are granted or issued upon, or that claim priority to, any and all applications described in (b) of this paragraph or that disclose or claim intellectual property described in (a) of this paragraph, in whole or in part; and

- (d) all claims for damages by reason of past infringement of any rights under the applications or patents described in (a), (b) or (c) of this paragraph (including provisional rights to reasonable royalties pursuant to 35 U.S.C. §154(d)) and the right to sue for and collect such damages and royalties for Assignees' own use.
- 2. Authorize and request the U.S. Patent and Trademark Office or any other U.S. or non-U.S. agency to issue to the Assignees any and all patent(s), or other rights or documents, resulting from the intellectual property, patent application(s) and patents described in paragraph 1 of this Assignment.
- 3. Agree to sign all papers and documents, including without limitation, applications, declarations, oaths and petitions, and, at the Assignees' expense, perform any other acts that are necessary in connection with prosecution of patent application(s) or intellectual property described in paragraph 1 of this Assignment and the enforcement of patent(s) or other rights resulting from such patent application(s) or intellectual property.
- 4. Agree that the terms, covenants, and conditions of this Assignment shall inure to the benefit of the Assignees, its successors, assigns and other legal representative, and shall be binding upon us, as well as our heirs, legal representatives, and assigns.
- 5. Promise and affirm that we have not entered, and will not enter, into any assignment, contract, or understanding that conflicts with this Assignment.
- 6. Authorize Kilpatrick Townsend & Stockton to insert above the application number and filing date of the above-described patent application when known.

Signed on the dates indicated beside our signatures.

Signature: 
CHAO ZHENG

Date: 2017. 11. 18

Signature: _____
WEI WANG

Date: _____

ASSIGNMENT

LOW CONTACT RESISTANCE SEMICONDUCTOR STRUCTURE AND METHOD FOR MANUFACTURING THE SAME

Attorney Docket No. 087720-052400US-1041630

Page 2 of 2

counterparts, continuations, continuations-in-part, divisionals, reissues, renewals, substitutes, extensions, reexaminations, post-grant reviews, inter partes reviews and supplemental examinations) that are granted or issued upon, or that claim priority to, any and all applications described in (b) of this paragraph or that disclose or claim intellectual property described in (a) of this paragraph, in whole or in part; and

(d) all claims for damages by reason of past infringement of any rights under the applications or patents described in (a), (b) or (c) of this paragraph (including provisional rights to reasonable royalties pursuant to 35 U.S.C. §154(d)) and the right to sue for and collect such damages and royalties for Assignees' own use.

2. Authorize and request the U.S. Patent and Trademark Office or any other U.S. or non-U.S. agency to issue to the Assignees any and all patent(s), or other rights or documents, resulting from the intellectual property, patent application(s) and patents described in paragraph 1 of this Assignment.
3. Agree to sign all papers and documents, including without limitation, applications, declarations, oaths and petitions, and, at the Assignees' expense, perform any other acts that are necessary in connection with prosecution of patent application(s) or intellectual property described in paragraph 1 of this Assignment and the enforcement of patent(s) or other rights resulting from such patent application(s) or intellectual property.
4. Agree that the terms, covenants, and conditions of this Assignment shall inure to the benefit of the Assignees, its successors, assigns and other legal representative, and shall be binding upon us, as well as our heirs, legal representatives, and assigns.
5. Promise and affirm that we have not entered, and will not enter, into any assignment, contract, or understanding that conflicts with this Assignment.
6. Authorize Kilpatrick Townsend & Stockton to insert above the application number and filing date of the above-described patent application when known.

Signed on the dates indicated beside our signatures.

Signature: _____
 CHAO ZHENG

Date: _____

Signature:  _____
 WEI WANG

Date: 2017. 11. 10

KILPATRICK TOWNSEND 70324990 1